

We Claim

1. A rewritable optical information recording medium comprising:
a substrate;
5 a recording layer, which is formed on said substrate and has the following composition:



10 wherein A is gold or silver; B is Sb or Bi; C is Te or Se; M is an element selected from the group consisting of Ti, Zr, Hf, V, Nb, Ta, Mg, W, Mo, B, N, C, P and Si; $0 < a < 13.0$; $10 < b < 87.0$; $8.0 < c < 50$; $0 < d < 30.0$; $0 < e < 8$; and $a+b+c+d+e=100$ atom%; and
15 a reflective layer, which is laminated on said recording layer and has a thickness of 1500Å to 4000Å.

2. The rewritable optical information recording medium according to claim 1, wherein the reflective layer is made from a material selected from the group consisting of gold, silver, copper, aluminum and alloys thereof.
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3. The rewritable optical information recording medium according to claim 1 further comprising upper and lower dielectric layers located between the reflective layer and the recording layer.
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4. The rewritable optical information recording medium according to claim 3, wherein the upper and lower dielectric layers are made from a material of ZnS-SiO₂ with ZnS in an amount of 70-90 mole%.
- 30 5. The rewritable optical information recording medium according to claim 3, wherein the upper and lower dielectric layers are made from a material selected from the group consisting of SiN, AlN, Ta₂O₅, ZnS, SiO₂, and Al₂O₃.
- 35 6. The rewritable optical information recording medium according to claim 1 further comprising a protective layer located on the recording layer.

7. The rewritable optical information recording medium according to claim 6, wherein the protective layer is made from a UV-curable resin.
- 5 8. The rewritable optical information recording medium according to claim 1, wherein the recording layer has a thickness of 50Å to 600Å.
- 10 9. The rewritable optical information recording medium according to claim 1, wherein the recording layer, the upper dielectric layer, the lower dielectric layer, and the reflective layer are laminated on the substrate by sputtering methods.